# HC<sub>2</sub>

# High current power inductors



#### **Product description**

- Compact footprint
- Designed for high density, high current/low voltage applications
- Foil technology that adds higher reliability factor over the traditional magnet wire used for higher frequency circuit designs
- Frequency Range up to 1MHz

#### **Applications**

- Distributed power systems DC-DC converters
- General-purpose low voltage supplies
- Computer systems
- Servers
- · Point of Load (POL) converters
- Industrial Equipment
- Networking/Telecom power supplies

#### **Environmental data**

- Storage temperature range (component): -40°C to +125°C
- Operating temperature range: -40°C to +125°C (ambient + self-temperature rise).
- Solder reflow temperature: J-STD-020D compliant





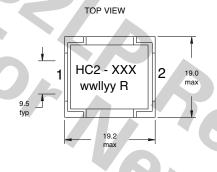


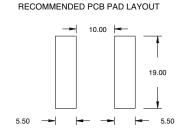
### **Product specifications**

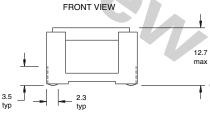
Part number	Part number (Tape and reel)	OCL¹ (μH) ±20%	I <sub>rms</sub> <sup>2</sup> amps	I <sub>sat</sub> amps	DCR (Ω) <sup>4</sup> maximum @ 20°C	Volt-μsec⁵ (V-μs)
HC2-R47-R	HC2-R47TR-R	.52	52.9	63.75	.0006	6.87
HC2-R68-R	HC2-R68TR-R	.63	52.9	50.00	.0006	6.87
HC2-1R0-R	HC2-1R0TR-R	1.15	33.0	42.50	.0013	10.31
HC2-2R2-R	HC2-2R2TR-R	2.00	24.3	31.90	.0023	13.75
HC2-4R7-R	HC2-4R7TR-R	4.55	17.0	21.25	.0046	20.62
HC2-6R0-R	HC2-6R0TR-R	6.00	17.0	16.50	.0046	20.62

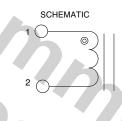
- 1. Open Circuit Inductance Test Parameters: 300kHz, 0.250 Vrms, 0.0 Adc
- 2. DC current for an approximate temperature change of 40°C without core loss. Derating is necessary for AC currents. PCB layout, trace thickness and width, air-flow and proximity of other heat generating components will affect the temperature rise. It is recommended that the temperature of the part not exceed 125°C under worst case operating conditions verified in the end application.
- 3. Peak current for approximately 30% rolloff.
- 4. Values @ 20°C
- Applied Volt-Time product (V-µs) across the inductor. This value represents the applied V-µs at 300KHz neccessary to generate a core loss equal to 10% of the total losses for 40°C temperature rise.

#### **Dimensions-mm**





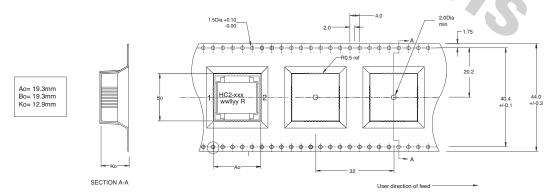




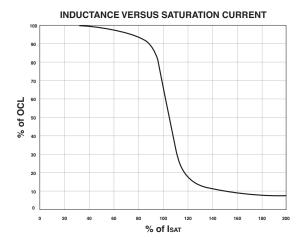
#### Packaging information (mm)

Bulk packaging: 45 parts per tray

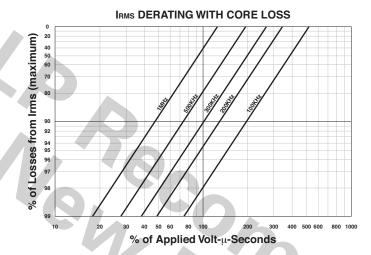
Tape and reel packaging: 110 parts per 13" diameter reel



#### Rolloff

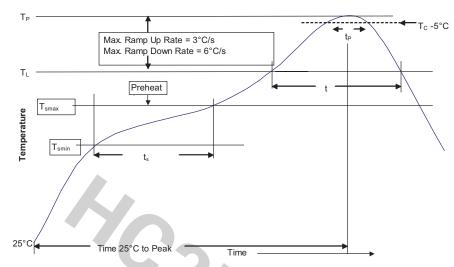


#### **Core loss**



5/9/20/20/

#### Solder reflow profile



 $-_{T_C}$  -5°C Table 1 - Standard SnPb Solder ( $T_c$ )

Package Thickness	Volume mm3 <350	Volume mm3 ≥350
<2.5mm)	235°C	220°C
≥2.5mm	220°C	220°C

Table 2 - Lead (Pb) Free Solder (Tc)

Package Thickness	Volume mm³ <350	Volume mm³ 350 - 2000	Volume mm³ >2000
<1.6mm	260°C	260°C	260°C
1.6 – 2.5mm	260°C	250°C	245°C
>2.5mm	250°C	245°C	245°C

## Reference JDEC J-STD-020D

Profile Feature	Standard SnPb Solder	Lead (Pb) Free Solder
Preheat and Soak • Temperature min. (T <sub>smin</sub> )	100°C	150°C
• Temperature max. (T <sub>smax</sub> )	150°C	200°C
• Time (T <sub>smin</sub> to T <sub>smax</sub> ) (t <sub>s</sub> )	60-120 Seconds	60-120 Seconds
Average ramp up rate T <sub>smax</sub> to T <sub>p</sub>	3°C/ Second Max.	3°C/ Second Max.
Liquidous temperature (TL) Time at liquidous (tL)	183°C 60-150 Seconds	217°C 60-150 Seconds
Peak package body temperature (Tp)*	Table 1	Table 2
Time (t <sub>p</sub> )** within 5 °C of the specified classification temperature (T <sub>C</sub> )	20 Seconds**	30 Seconds**
Average ramp-down rate (T <sub>p</sub> to T <sub>Smax</sub> )	6°C/ Second Max.	6°C/ Second Max.
Time 25°C to Peak Temperature	6 Minutes Max.	8 Minutes Max.
* Tolerance for peak profile temperature $(T_p)$ is defined as a supplier minimum and a user maximum.  ** Tolerance for time at peak profile temperature $(t_p)$ is defined as a supplier minimum and a user maximum.	es,	9000

<sup>\*</sup> Tolerance for peak profile temperature (T<sub>n</sub>) is defined as a supplier minimum and a user maximum.

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<sup>\*\*</sup> Tolerance for time at peak profile temperature (t<sub>p</sub>) is defined as a supplier minimum and a user maximum.